## (12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

## (19) World Intellectual Property Organization International Bureau



## 

(43) International Publication Date 31 March 2005 (31.03.2005)

## (10) International Publication Number WO 2005/028360 A1

- (51) International Patent Classification7: B82B 3/00, H01J 37/317, H01L 21/26, 21/285, 21/311, 21/3213
- (21) International Application Number:

PCT/NZ2004/000230

(22) International Filing Date:

23 September 2004 (23.09.2004)

(25) Filing Language:

**English** 

(26) Publication Language:

**English** 

- (30) Priority Data: 528448
- 24 September 2003 (24.09.2003)
- (71) Applicant (for all designated States except US): NAN-OCLUSTER DEVICES LIMITED [NZ/NZ]; Forestry School Building, Forestry Road, Elam, Christchurch, 8004 (NZ).
- (72) Inventors; and
- (75) Inventors/Applicants (for US only): BROWN, Simon, Anthony [NZ/NZ]; 81 Hinau Street, Riccarton,

Christchurch, 8004 (NZ). PARTRIDGE, James, Gordon [GB/NZ]; Unit 5, 477 Madras Street, St Albans, Christchurch, 8001 (NZ).

- (74) Agents: ADAMS, Matthew, D et al.; A J Park, 6th Floor Huddart Parker Building, PO Box 949, Wellington, 6015
- (81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH. PL. PT. RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.
- (84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH, GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI,

[Continued on next page]

(54) Title: ETCH MASKS BASED ON TEMPLATE-ASSEMBLED NANOCLUSTERS

Thermally Oxidised SI

Ar Plasma Etch

Anisotropic Si etching

Thermally Oxidised SI

Cluster and Au/Ti wires

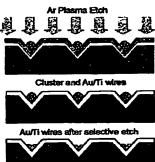
Au/Ti wires after selective etch

Motallised and Oxidised SI

Au/Ti wires after selective etch

atomic clusters (e.g. antimony or bismuth) into V-grooves. These structures, preferably in the form of nanowires, are used as etching masks for the subsequent etching of the substrate. In an embodiment the V-grooves are metallised (e.g. with titamium or sold!) prior





atomic clusters (e.g. antimony or bismuth) into V-grooves. These structures, preferably in the form of nanowires, are used as etching masks for the subsequent etching of the substrate. In an embodiment the V-grooves are metallised (e.g. with titanium or gold) prior masks for the subsequent etching of the substrate. In an embodiment the V-grooves are metallised (e.g. with titanium or gold) prior to the deposition of the clusters. In this case the use of the nanostructures (e.g. antimony or bismuth) as an etching mask results in the formation of nanostructures of the underlying metal (e.g. titanium or gold). In this way the dimensions of the nanowires are transferred into the underlying metal film and the method allows fabrication of nanowires from materials (e.g. titanium or gold) that cannot be deposited as clusters.

BEST AVAILABLE COPY